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Preferred Devices

Dual Common Base-Collector Bias Resistor Transistors

NPN and PNP Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. The NSTB1005DXV5T1 contains two complementary BRT devices are housed in the SOT-553 package which is ideal for low power surface mount applications where board space is at a premium.

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7 inch Tape and Reel
- Lead Free

MAXIMUM RATINGS ($T_A = 25^{\circ}C$ unless otherwise noted, common for Q_1 and Q_2 , – minus sign for Q_1 (PNP) omitted)

Rating	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V _{CEO}	50	Vdc
Collector Current	Ι _C	100	mAdc

THERMAL CHARACTERISTICS

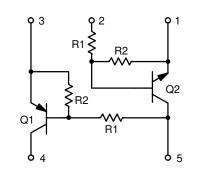
Characteristic (One Junction Heated)	Symbol	Мах	Unit	
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D	357 (Note 1) 2.9 (Note 1)	mW mW/°C	
Thermal Resistance – Junction-to-Ambient	R _{θJA}	350 (Note 1)	°C/W	
Characteristic (Both Junctions Heated)	Symbol	Мах	Unit	
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D	500 (Note 1) 4.0 (Note 1)	mW mW/°C	
Thermal Resistance – Junction-to-Ambient	R _{θJA}	250 (Note 1)	°C/W	
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C	

1. FR-4 @ Minimum Pad



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CASE 463B

MARKING DIAGRAM



UC = Specific Device Code D = Date Code

ORDERING INFORMATION

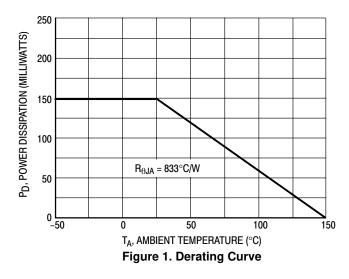
Device	Package	Shipping [†]
NSTB1005DXV5T1	SOT-553	4 mm pitch 4000/Tape & Reel
NSTB1005DXV5T5	SOT-553	2 mm pitch 8000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

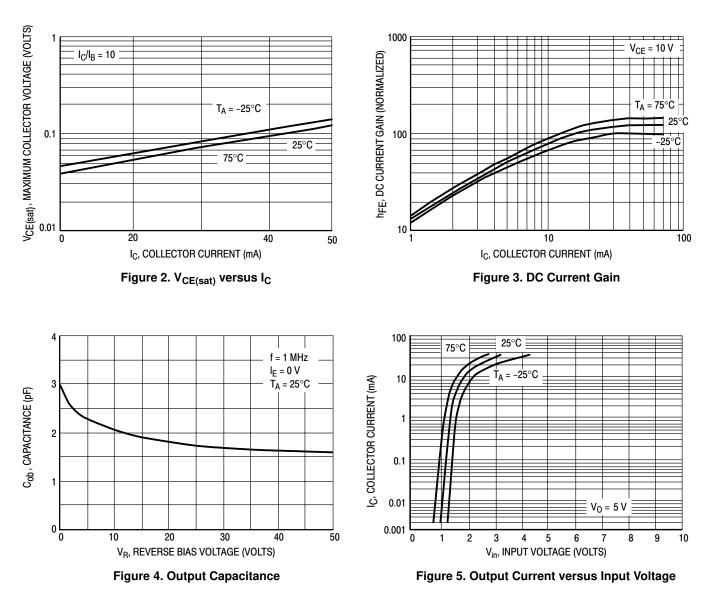
Preferred devices are recommended choices for future use and best overall value.

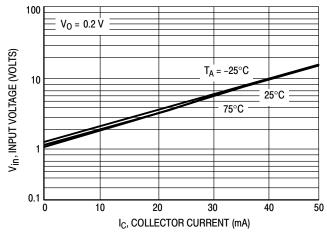
Characteristic	Symbol	Min	Тур	Max	Unit
Q1 TRANSISTOR: PNP – OFF CHARACTERISTICS					
Collector–Base Cutoff Current ($V_{CB} = 50 \text{ V}, I_E = 0$)	I _{CBO}	-	-	100	nAdc
Collector–Emitter Cutoff Current ($V_{CE} = 50 \text{ V}, I_B = 0$)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current	I _{EBO}	-	-	0.1	mAdc
Collector–Base Breakdown Voltage ($I_C = 10 \ \mu A$, $I_E = 0$)	V _{(BR)CBO}	50	-	-	Vdc
Collector–Emitter Breakdown Voltage ($I_C = 2.0 \text{ mA}, I_B = 0$)	V _{(BR)CEO}	50	-	-	Vdc
ON CHARACTERISTICS		•			•
DC Current Gain	h _{FE}	80	140	-	
Collector–Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_E = 0.3 \text{ mA}$)	V _{CE(sat)}	-	-	0.25	Vdc
Output Voltage (on) (V_{CC} = 5.0 V, V_B = 3.5 V, R_L = 1.0 k Ω)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) (V_{CC} = 5.0 V, V_B = 0.5 V, RL = 1.0 k Ω)	V _{OH}	4.9	-	-	Vdc
Input Resistor	R1	32.9	47	61.1	kΩ
Resistor Ratio	R ₁ /R ₂	0.8	1.0	1.2	
Q2 TRANSISTOR: NPN – OFF CHARACTERISTICS		•			
Collector-Base Cutoff Current ($V_{CB} = 50 \text{ V}, I_E = 0$)	I _{CBO}	-	-	100	nAdc
Collector-Emitter Cutoff Current ($V_{CB} = 50 \text{ V}, I_B = 0$)	I _{CEO}	-	-	500	nAdc
Emitter-Base Cutoff Current $(V_{EB} = 6.0, I_C = 5.0 \text{ mA})$	I _{EBO}	-	-	0.1	mAdc
ON CHARACTERISTICS					
Collector-Base Breakdown Voltage (I _C = 10 μ A, I _E = 0)	V _{(BR)CBO}	50	-	-	Vdc
Collector-Emitter Breakdown Voltage ($I_C = 2.0 \text{ mA}, I_B = 0$)	V _{(BR)CEO}	50	-	-	Vdc
DC Current Gain $(V_{CE} = 10 \text{ V}, I_C = 5.0 \text{ mA})$	h _{FE}	80	140	-	
Collector–Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$)	V _{CE(SAT)}	-	-	0.25	Vdc
Output Voltage (on) (V_{CC} = 5.0 V, V_B = 2.5 V, R_L = 1.0 k\Omega)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) (V_{CC} = 5.0 V, V_B = 0.5 V, R_L = 1.0 k\Omega)	V _{OH}	4.9	- 1	-	Vdc
Input Resistor	R1	33	47	61	kΩ
Resistor Ratio	R1/R2	0.8	1.0	1.2	

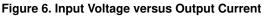
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)



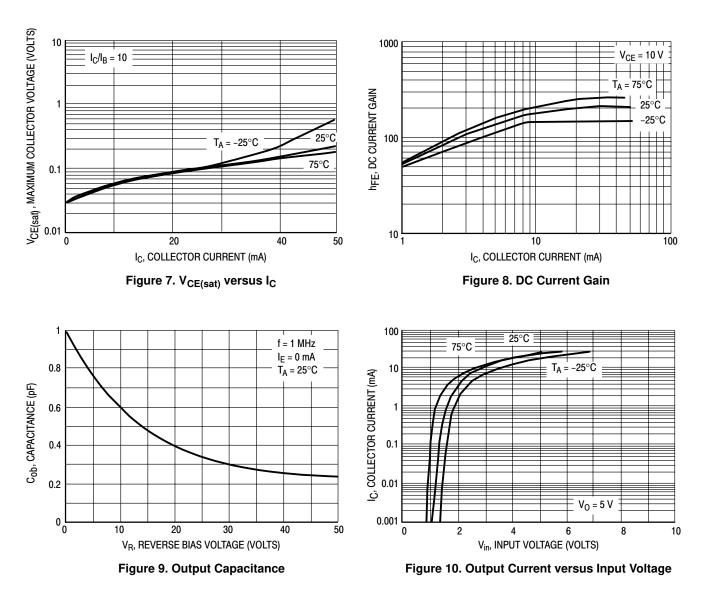
TYPICAL ELECTRICAL CHARACTERISTICS – PNP TRANSISTOR







TYPICAL ELECTRICAL CHARACTERISTICS - NPN TRANSISTOR



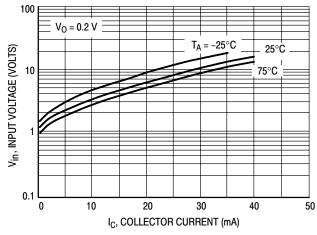
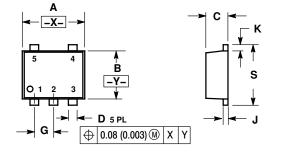


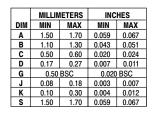
Figure 11. Input Voltage versus Output Current

PACKAGE DIMENSIONS

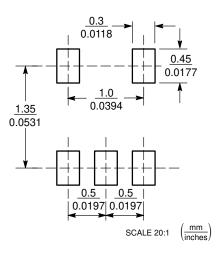
SOT-553 **XV5 SUFFIX** 5-LEAD PACKAGE CASE 463B-01 **ISSUE A**

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL MATERIAL.





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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